



Welcome to **E-XFL.COM** 

# Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	359200
Number of Logic Elements/Cells	952000
Total RAM Bits	53248000
Number of I/O	600
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1760-BBGA, FCBGA
Supplier Device Package	1760-HBGA (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxebbr1h43i2n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Page 6 Electrical Characteristics

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 2 of 2)

Symbol	Description	Condition	Min <sup>(4)</sup>	Тур	Max <sup>(4)</sup>	Unit
t	Power supply ramp time	Standard POR	200 μs	_	100 ms	_
LRAMP	Fower supply rainp line	Fast POR	200 μs	_	4 ms	_

#### Notes to Table 6:

- (1)  $V_{CCPD}$  must be 2.5 V when  $V_{CCIO}$  is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V.  $V_{CCPD}$  must be 3.0 V when  $V_{CCIO}$  is 3.0 V.
- (2) If you do not use the design security feature in Stratix V devices, connect V<sub>CCBAT</sub> to a 1.2- to 3.0-V power supply. Stratix V power-on-reset (POR) circuitry monitors V<sub>CCBAT</sub>. Stratix V devices will not exit POR if V<sub>CCBAT</sub> stays at logic low.
- (3) C2L and I2L can also be run at 0.90 V for legacy boards that were designed for the C2 and I2 speed grades.
- (4) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 7 lists the transceiver power supply recommended operating conditions for Stratix V GX, GS, and GT devices.

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 1 of 2)

Symbol	Description	Devices	Minimum <sup>(4)</sup>	Typical	Maximum <sup>(4)</sup>	Unit
V <sub>CCA_GXBL</sub>	Transceiver channel PLL power supply (left	GX, GS, GT	2.85	3.0	3.15	V
(1), (3)	side)	७४, ७७, ७१	2.375	2.5	2.625	V
V <sub>CCA_GXBR</sub>	Transceiver channel PLL power supply (right	GX, GS	2.85	3.0	3.15	V
$(1), (\overline{3})$	side)	রম, রহ	2.375	2.5	2.625	V
V <sub>CCA_GTBR</sub>	Transceiver channel PLL power supply (right side)	GT	2.85	3.0	3.15	V
	Transceiver hard IP power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V <sub>CCHIP_L</sub>	Transceiver hard IP power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver hard IP power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
$V_{\text{CCHIP}\_R}$	Transceiver hard IP power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver PCS power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V <sub>CCHSSI_L</sub>	Transceiver PCS power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver PCS power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V <sub>CCHSSI_R</sub>	Transceiver PCS power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
			0.82	0.85	0.88	
V <sub>CCR_GXBL</sub>	Receiver analog power supply (left side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	Treceiver arialog power supply (left side)	un, us, ui	0.97	1.0	1.03	v
			1.03	1.05	1.07	

Electrical Characteristics Page 7

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 2 of 2)

Symbol	Description	Devices	Minimum <sup>(4)</sup>	Typical	Maximum <sup>(4)</sup>	Unit
			0.82	0.85	0.88	
V <sub>CCR_GXBR</sub>	Receiver analog power supply (right side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	neceiver analog power supply (right side)	ux, us, u1	0.97	1.0	1.03	v
			1.03	1.05	1.07	
V <sub>CCR_GTBR</sub>	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
			0.82	0.85	0.88	
V <sub>CCT_GXBL</sub>	Transmitter analog newer cupply (left side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	Transmitter analog power supply (left side)	ux, us, u1	0.97	1.0	1.03	V
			1.03	1.05	1.07	
			0.82	0.85	0.88	
V <sub>CCT_GXBR</sub>	Transmitter analog power supply (right side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	Transmitter analog power supply (right side)	ux, us, u1	0.97	1.0	1.03	V
			1.03	1.05	1.07	
V <sub>CCT_GTBR</sub>	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V <sub>CCL_GTBR</sub>	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
V <sub>CCH_GXBL</sub>	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
V <sub>CCH_GXBR</sub>	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

#### Notes to Table 7:

<sup>(1)</sup> This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.

<sup>(2)</sup> Refer to Table 8 to select the correct power supply level for your design.

<sup>(3)</sup> When using ATX PLLs, the supply must be 3.0 V.

<sup>(4)</sup> This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Page 12 Electrical Characteristics

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2) (1)

Symbol	Description	V <sub>CCIO</sub> (V)	Typical	Unit
		3.0	0.189	
		2.5	0.208	
dR/dT	OCT variation with temperature without recalibration	1.8	0.266	%/°C
	Willout recalibration	1.5	0.273	1
		1.2	0.317	

#### Note to Table 13:

(1) Valid for a  $V_{\text{CCIO}}$  range of  $\pm 5\%$  and a temperature range of  $0^\circ$  to  $85^\circ\text{C}.$ 

### **Pin Capacitance**

Table 14 lists the Stratix V device family pin capacitance.

**Table 14. Pin Capacitance for Stratix V Devices** 

Symbol	Description	Value	Unit
C <sub>IOTB</sub>	Input capacitance on the top and bottom I/O pins	6	pF
C <sub>IOLR</sub>	Input capacitance on the left and right I/O pins	6	pF
C <sub>OUTFB</sub>	Input capacitance on dual-purpose clock output and feedback pins	6	pF

### **Hot Socketing**

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15. Hot Socketing Specifications for Stratix V Devices

Symbol	Description	Maximum
I <sub>IOPIN (DC)</sub>	DC current per I/O pin	300 μΑ
I <sub>IOPIN (AC)</sub>	AC current per I/O pin	8 mA <sup>(1)</sup>
I <sub>XCVR-TX (DC)</sub>	DC current per transceiver transmitter pin	100 mA
I <sub>XCVR-RX (DC)</sub>	DC current per transceiver receiver pin	50 mA

### Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns,  $|I_{IOPIN}| = C dv/dt$ , in which C is the I/O pin capacitance and dv/dt is the slew rate.

Electrical Characteristics Page 13

## **Internal Weak Pull-Up Resistor**

Table 16 lists the weak pull-up resistor values for Stratix V devices.

Table 16. Internal Weak Pull-Up Resistor for Stratix V Devices (1), (2)

Symbol	Description	V <sub>CC10</sub> Conditions (V) <sup>(3)</sup>	Value <sup>(4)</sup>	Unit
		3.0 ±5%	25	kΩ
		2.5 ±5%	25	kΩ
	Value of the I/O pin pull-up resistor before	1.8 ±5%	25	kΩ
R <sub>PU</sub>	and during configuration, as well as user mode if you enable the programmable	1.5 ±5%	25	kΩ
	pull-up resistor option.	1.35 ±5%	25	kΩ
		1.25 ±5%	25	kΩ
		1.2 ±5%	25	kΩ

#### Notes to Table 16:

- (1) All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins.
- (2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 k $\Omega$ .
- (3) The pin pull-up resistance values may be lower if an external source drives the pin higher than  $V_{\text{CCIO}}$ .
- (4) These specifications are valid with a ±10% tolerance to cover changes over PVT.

## I/O Standard Specifications

Table 17 through Table 22 list the input voltage ( $V_{IH}$  and  $V_{IL}$ ), output voltage ( $V_{OH}$  and  $V_{OL}$ ), and current drive characteristics ( $I_{OH}$  and  $I_{OL}$ ) for various I/O standards supported by Stratix V devices. These tables also show the Stratix V device family I/O standard specifications. The  $V_{OL}$  and  $V_{OH}$  values are valid at the corresponding  $I_{OH}$  and  $I_{OL}$ , respectively.

For an explanation of the terms used in Table 17 through Table 22, refer to "Glossary" on page 65. For tolerance calculations across all SSTL and HSTL I/O standards, refer to Altera knowledge base solution rd07262012\_486.

Table 17. Single-Ended I/O Standards for Stratix V Devices

I/O		V <sub>CCIO</sub> (V)		VII	_(V)	V <sub>IH</sub>	(V)	V <sub>OL</sub> (V)	V <sub>OH</sub> (V)	I <sub>OL</sub>	I <sub>OH</sub>
Standard	Min	Тур	Max	Min	Max	Min	Max	Max	Min	(mĀ)	(mA)
LVTTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	-2
LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.2	V <sub>CCIO</sub> - 0.2	0.1	-0.1
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	1	-1
1.8 V	1.71	1.8	1.89	-0.3	0.35 * V <sub>CCIO</sub>	0.65 * V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.45	V <sub>CCIO</sub> – 0.45	2	-2
1.5 V	1.425	1.5	1.575	-0.3	0.35 * V <sub>CCIO</sub>	0.65 * V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.25 * V <sub>CCIO</sub>	0.75 * V <sub>CCIO</sub>	2	-2
1.2 V	1.14	1.2	1.26	-0.3	0.35 * V <sub>CCIO</sub>	0.65 * V <sub>CCIO</sub>	V <sub>CCIO</sub> + 0.3	0.25 * V <sub>CCIO</sub>	0.75 * V <sub>CCIO</sub>	2	-2

Page 16 Electrical Characteristics

Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 2 of 2)

I/O				V <sub>DIF(</sub>	<sub>DC)</sub> (V)	V <sub>X(AC)</sub> (V)				V <sub>CM(DC)</sub> (V	V <sub>DIF(AC)</sub> (V)		
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V <sub>CCIO</sub> + 0.3	_	0.5* V <sub>CCIO</sub>	_	0.4* V <sub>CCIO</sub>	0.5* V <sub>CCIO</sub>	0.6* V <sub>CCIO</sub>	0.3	V <sub>CCIO</sub> + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5*V <sub>CCIO</sub> - 0.12	0.5* V <sub>CCIO</sub>	0.5*V <sub>CCIO</sub> + 0.12	0.4* V <sub>CCIO</sub>	0.5* V <sub>CCIO</sub>	0.6* V <sub>CCIO</sub>	0.44	0.44

Table 22. Differential I/O Standard Specifications for Stratix V Devices (7)

I/O	V <sub>CCIO</sub> (V) <sup>(10)</sup>				V <sub>ID</sub> (mV) <sup>(8)</sup>			$V_{ICM(DC)}$ (V)		V <sub>o</sub>	<sub>D</sub> (V) (	6)	V <sub>OCM</sub> (V) <sup>(6)</sup>		
Standard	Min	Тур	Max	Min	Condition	Max	Min	Condition	Max	Min	Тур	Max	Min	Тур	Max
PCML	Trar	Transmitter, receiver, and input reference clock pins of the high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to Table 23 on page 18.													. For
2.5 V	2.375	2.5	2.625	100	V <sub>CM</sub> =	_	0.05	D <sub>MAX</sub> ≤ 700 Mbps	1.8	0.247	_	0.6	1.125	1.25	1.375
LVDS (1)	2.373	2.3	2.023	100	1.25 V		1.05	D <sub>MAX</sub> > 700 Mbps	1.55	0.247	_	0.6	1.125	1.25	1.375
BLVDS (5)	2.375	2.5	2.625	100	_	_	_	_	_	_	_	_	_	_	_
RSDS (HIO) <sup>(2)</sup>	2.375	2.5	2.625	100	V <sub>CM</sub> = 1.25 V	_	0.3	_	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini- LVDS (HIO) (3)	2.375	2.5	2.625	200	_	600	0.4	_	1.325	0.25	_	0.6	1	1.2	1.4
LVPECL (4	_	_	_	300	_	_	0.6	D <sub>MAX</sub> ≤ 700 Mbps	1.8	_	_	_	_	_	
), (9)	_	_	_	300	_	_	1	D <sub>MAX</sub> > 700 Mbps	1.6	_	_	_	_	_	_

#### Notes to Table 22:

- (1) For optimized LVDS receiver performance, the receiver voltage input range must be between 1.0 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.
- (2) For optimized RSDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.45 V.
- (3) For optimized Mini-LVDS receiver performance, the receiver voltage input range must be between 0.3 V to 1.425 V.
- (4) For optimized LVPECL receiver performance, the receiver voltage input range must be between 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.
- (5) There are no fixed  $V_{\text{ICM}}$ ,  $V_{\text{OD}}$ , and  $V_{\text{OCM}}$  specifications for BLVDS. They depend on the system topology.
- (6) RL range:  $90 \le RL \le 110 \Omega$ .
- (7) The 1.4-V and 1.5-V PCML transceiver I/O standard specifications are described in "Transceiver Performance Specifications" on page 18.
- (8) The minimum VID value is applicable over the entire common mode range, VCM.
- (9) LVPECL is only supported on dedicated clock input pins.
- (10) Differential inputs are powered by VCCPD which requires 2.5  $\rm V.$

## **Power Consumption**

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator and the Quartus<sup>®</sup> II PowerPlay Power Analyzer feature.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 4 of 7)

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Trai	nsceive Grade		Trai	nsceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	85– $\Omega$ setting	_	85 ± 30%	_	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on- chip termination resistors (21)	100–Ω setting	_	100 ± 30%	_	_	100 ± 30%	_	_	100 ± 30%	_	Ω
	120–Ω setting	_	120 ± 30%		_	120 ± 30%		_	120 ± 30%	_	Ω
	150-Ω setting	_	150 ± 30%	_	_	150 ± 30%	_	_	150 ± 30%	_	Ω
	V <sub>CCR_GXB</sub> = 0.85 V or 0.9 V full bandwidth	_	600	_	_	600	_	_	600	_	mV
V <sub>ICM</sub> (AC and DC	$\begin{array}{c} V_{CCR\_GXB} = \\ 0.85 \text{ V or } 0.9 \\ \text{V} \\ \text{half} \\ \text{bandwidth} \end{array}$	_	600	_	_	600	_	_	600	_	mV
coupled)	V <sub>CCR_GXB</sub> = 1.0 V/1.05 V full bandwidth	_	700	_	_	700	_	_	700	_	mV
	V <sub>CCR_GXB</sub> = 1.0 V half bandwidth	_	750	_	_	750	_	_	750	_	mV
t <sub>LTR</sub> (11)	_	_	_	10	_	_	10	_	_	10	μs
t <sub>LTD</sub> (12)	_	4	_		4			4		_	μs
t <sub>LTD_manual</sub> (13)	_	4	_		4	_		4	_		μs
t <sub>LTR_LTD_manual</sub> (14)	_	15	_	_	15		_	15		_	μs
Run Length	_		_	200		_	200	_		200	UI
Programmable equalization (AC Gain) <sup>(10)</sup>	Full bandwidth (6.25 GHz) Half bandwidth (3.125 GHz)	_	_	16	_	_	16	_	_	16	dB

Page 24 Switching Characteristics

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 7 of 7)

Symbol/ Description	Conditions	Trai	Transceiver Speed Grade 1		Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t <sub>pll_lock</sub> (16)	_	_	_	10	_	_	10	_	_	10	μs

#### Notes to Table 23:

- (1) Speed grades shown in Table 23 refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the  $V_{CCR\_GXB}$  power supply level.
- (3) This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates up to 6.5 Gbps, you can connect this supply to 0.85 V.
- (4) This supply follows VCCR\_GXB.
- (5) The device cannot tolerate prolonged operation at this absolute maximum.
- (6) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (7) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (8) The input reference clock frequency options depend on the data rate and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (11) t<sub>LTR</sub> is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (12) t<sub>I TD</sub> is time required for the receiver CDR to start recovering valid data after the rx\_is\_lockedtodata signal goes high.
- (13) t<sub>LTD\_manual</sub> is the time required for the receiver CDR to start recovering valid data after the rx\_is\_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (14) t<sub>LTR\_LTD\_manual</sub> is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx\_is\_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (15)  $t_{pll\ powerdown}$  is the PLL powerdown minimum pulse width.
- (16) t<sub>nll lock</sub> is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (18) The maximum peak to peak differential input voltage V<sub>ID</sub> after device configuration is equal to 4 × (absolute V<sub>MAX</sub> for receiver pin V<sub>ICM</sub>).
- (19) For ES devices,  $R_{REF}$  is 2000  $\Omega$  ±1%.
- (20) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20\*log(f/622).
- (21) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (22) Refer to Figure 2.
- (23) For oversampling designs to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (24) I3YY devices can achieve data rates up to 10.3125 Gbps.
- (25) When you use fPLL as a TXPLL of the transceiver.
- (26) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
- (27) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

Table 24 shows the maximum transmitter data rate for the clock network.

Table 24. Clock Network Maximum Data Rate Transmitter Specifications (1)

		ATX PLL			CMU PLL (2)	)		fPLL	
Clock Network	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span
x1 <sup>(3)</sup>	14.1	_	6	12.5	_	6	3.125	_	3
x6 <sup>(3)</sup>	_	14.1	6	_	12.5	6	_	3.125	6
x6 PLL Feedback <sup>(4)</sup>	_	14.1	Side- wide	_	12.5	Side- wide	_	_	_
xN (PCIe)	_	8.0	8	_	5.0	8	_	_	_
xN (Native PHY IP)	8.0	8.0	Up to 13 channels above and below PLL	7.99	7.99	Up to 13 channels above	3.125	3.125	Up to 13 channels above
XIV (IVALIVE PRY IP)	_	8.01 to 9.8304	Up to 7 channels above and below PLL	7.99	7.99	and below PLL	J. 125	3.123	and below PLL

#### Notes to Table 24:

<sup>(1)</sup> Valid data rates below the maximum specified in this table depend on the reference clock frequency and the PLL counter settings. Check the MegaWizard message during the PHY IP instantiation.

<sup>(2)</sup> ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.

<sup>(3)</sup> Channel span is within a transceiver bank.

<sup>(4)</sup> Side-wide channel bonding is allowed up to the maximum supported by the PHY IP.

Page 26 Switching Characteristics

Table 25 shows the approximate maximum data rate using the standard PCS.

Table 25. Stratix V Standard PCS Approximate Maximum Date Rate (1), (3)

Made (2)	Transceiver	PMA Width	20	20	16	16	10	10	8	8
Mode <sup>(2)</sup>	Speed Grade	PCS/Core Width	40	20	32	16	20	10	16	8
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C3, I3, I3L core speed grade	9.8	9.0	7.84	7.2	5.3	4.7	4.24	3.76
FIFO		C1, C2, C2L, I2, I2L core speed grade	8.5	8.5	8.5	8.5	6.5	5.8	5.2	4.72
	3	I3YY core speed grade	10.3125	10.3125	7.84	7.2	5.3	4.7	4.24	3.76
	3	C3, I3, I3L core speed grade	8.5	8.5	7.84	7.2	5.3	4.7	4.24	3.76
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.8	4.2	3.84	3.44
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C3, I3, I3L core speed grade	9.8	9.0	7.92	7.2	4.9	4.5	3.96	3.6
Register		C1, C2, C2L, I2, I2L core speed grade	10.3125	10.3125	10.3125	10.3125	6.1	5.7	4.88	4.56
	3	I3YY core speed grade	10.3125	10.3125	7.92	7.2	4.9	4.5	3.96	3.6
	3	C3, I3, I3L core speed grade	8.5	8.5	7.92	7.2	4.9	4.5	3.96	3.6
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.4	4.1	3.52	3.28

### Notes to Table 25:

<sup>(1)</sup> The maximum data rate is in Gbps.

<sup>(2)</sup> The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

<sup>(3)</sup> The maximum data rate is also constrained by the transceiver speed grade. Refer to Table 1 for the transceiver speed grade.

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 4 of 5)  $^{(1)}$ 

Symbol/	Conditions		Transceive peed Grade			Transceive Deed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Data rate	GT channels	19,600	_	28,050	19,600	_	25,780	Mbps
Differential on-chip	GT channels	_	100	_		100	<u> </u>	Ω
termination resistors	GX channels			•	(8)		<u>'</u>	
\/	GT channels	_	500	_	_	500	_	mV
V <sub>OCM</sub> (AC coupled)	GX channels			•	(8)		<u>'</u>	
Diag/Fall time	GT channels	_	15	_	_	15	_	ps
Rise/Fall time	GX channels		<u>I</u>		(8)			
Intra-differential pair skew	GX channels				(8)			
Intra-transceiver block transmitter channel-to- channel skew	GX channels				(8)			
Inter-transceiver block transmitter channel-to- channel skew	GX channels				(8)			
CMU PLL								
Supported Data Range	_	600	_	12500	600	_	8500	Mbps
t <sub>pll_powerdown</sub> (13)	_	1	_	_	1	_	_	μs
t <sub>pll_lock</sub> (14)	_	_	_	10	_	_	10	μs
ATX PLL								
	VCO post- divider L=2	8000	_	12500	8000	_	8500	Mbps
	L=4	4000	_	6600	4000	_	6600	Mbps
Supported Data Rate	L=8	2000	_	3300	2000	_	3300	Mbps
Range for GX Channels	L=8, Local/Central Clock Divider =2	1000	_	1762.5	1000	_	1762.5	Mbps
Supported Data Rate Range for GT Channels	VCO post- divider L=2	9800	_	14025	9800	_	12890	Mbps
t <sub>pll_powerdown</sub> (13)	_	1	_	_	1	_	_	μs
t <sub>pll_lock</sub> (14)	_	_	_	10	_	_	10	μs
fPLL			•					
Supported Data Range	_	600	_	3250/ 3.125 <sup>(23)</sup>	600	_	3250/ 3.125 <sup>(23)</sup>	Mbps
t <sub>pll_powerdown</sub> (13)	_	1	_	_	1	_	_	μs

Figure 6 shows the Stratix V DC gain curves for GT channels.

### Figure 6. DC Gain Curves for GT Channels

### **Transceiver Characterization**

This section summarizes the Stratix V transceiver characterization results for compliance with the following protocols:

- Interlaken
- 40G (XLAUI)/100G (CAUI)
- 10GBase-KR
- QSGMII
- XAUI
- SFI
- Gigabit Ethernet (Gbe / GIGE)
- SPAUI
- Serial Rapid IO (SRIO)
- CPRI
- OBSAI
- Hyper Transport (HT)
- SATA
- SAS
- CEI

Page 40 Switching Characteristics

Table 31. PLL Specifications for Stratix V Devices (Part 2 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
<b>→</b> (3) (4)	Input clock cycle-to-cycle jitter (f <sub>REF</sub> ≥ 100 MHz)	_	_	0.15	UI (p-p)
t <sub>INCCJ</sub> (3), (4)	Input clock cycle-to-cycle jitter (f <sub>REF</sub> < 100 MHz)	-750		+750	ps (p-p)
+ (5)	Period Jitter for dedicated clock output ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	175 <sup>(1)</sup>	ps (p-p)
t <sub>OUTPJ_DC</sub> (5)	Period Jitter for dedicated clock output (f <sub>OUT</sub> < 100 MHz)	_	_	17.5 <sup>(1)</sup>	mUI (p-p)
+ (5)	Period Jitter for dedicated clock output in fractional PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	250 <sup>(11)</sup> , 175 <sup>(12)</sup>	ps (p-p)
t <sub>FOUTPJ_DC</sub> (5)	Period Jitter for dedicated clock output in fractional PLL (f <sub>OUT</sub> < 100 MHz)	_	_	25 <sup>(11)</sup> , 17.5 <sup>(12)</sup>	mUI (p-p)
+ (5)	Cycle-to-Cycle Jitter for a dedicated clock output $(f_{OUT} \ge 100 \text{ MHz})$	_	_	175	ps (p-p)
t <sub>outccj_dc</sub> (5)	Cycle-to-Cycle Jitter for a dedicated clock output (f <sub>OUT</sub> < 100 MHz)	_	_	17.5	mUI (p-p)
<b>+</b> (5)	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	250 <sup>(11)</sup> , 175 <sup>(12)</sup>	ps (p-p)
t <sub>FOUTCCJ_DC</sub> <sup>(5)</sup>	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL (f <sub>OUT</sub> < 100 MHz)+	_	_	25 <sup>(11)</sup> , 17.5 <sup>(12)</sup>	mUI (p-p)
t <sub>OUTPJ_IO</sub> (5),	Period Jitter for a clock output on a regular I/O in integer PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	600	ps (p-p)
(8)	Period Jitter for a clock output on a regular I/O (f <sub>OUT</sub> < 100 MHz)	_	_	60	mUI (p-p)
t <sub>FOUTPJ 10</sub> (5),	Period Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	600 (10)	ps (p-p)
(8), (11)	Period Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT}$ < 100 MHz)	_	_	60 (10)	mUI (p-p)
t <sub>outccj_10</sub> (5),	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ( $f_{OUT} \ge 100$ MHz)	_	_	600	ps (p-p)
(8)	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ( $f_{OUT}$ < 100 MHz)	_	_	60 (10)	mUI (p-p)
t <sub>FOUTCCJ_IO</sub>	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT} \ge 100$ MHz)	_	_	600 (10)	ps (p-p)
(8), (11)	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ( $f_{\text{OUT}}$ < 100 MHz)	_	_	60	mUI (p-p)
t <sub>CASC_OUTPJ_DC</sub>	Period Jitter for a dedicated clock output in cascaded PLLs ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	175	ps (p-p)
(5), (6)	Period Jitter for a dedicated clock output in cascaded PLLs (f <sub>OUT</sub> < 100 MHz)	_	_	17.5	mUI (p-p)
f <sub>DRIFT</sub>	Frequency drift after PFDENA is disabled for a duration of 100 $\mu s$	_	_	±10	%
dK <sub>BIT</sub>	Bit number of Delta Sigma Modulator (DSM)	8	24	32	Bits
k <sub>VALUE</sub>	Numerator of Fraction	128	8388608	2147483648	_

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 4 of 4)

Cumbal	Conditions		C1		C2,	C2L, I	2, I2L	C3,	I3, I3I	., I3YY	C4,14			Unit
Symbol	Conuntions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Ullit
	SERDES factor J = 3 to 10	(6)	_	(8)	(6)		(8)	(6)		(8)	(6)	_	(8)	Mbps
f <sub>HSDR</sub> (data rate)	SERDES factor J = 2, uses DDR Registers	(6)		(7)	(6)		(7)	(6)		(7)	(6)		(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
DPA Mode														
DPA run length	_		_	1000 0			1000 0	_		1000 0	_	_	1000 0	UI
Soft CDR mode	•													
Soft-CDR PPM tolerance	_	_	_	300	_	_	300	_	_	300	_	_	300	± PPM
Non DPA Mode	,													
Sampling Window	_	_	_	300	_		300	_		300	_	_	300	ps

#### Notes to Table 36:

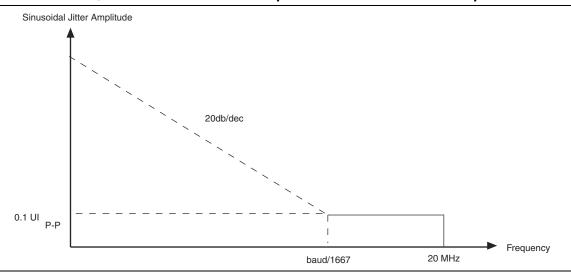
- (1) When J = 3 to 10, use the serializer/deserializer (SERDES) block.
- (2) When J = 1 or 2, bypass the SERDES block.
- (3) This only applies to DPA and soft-CDR modes.
- (4) Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.
- (5) This is achieved by using the **LVDS** clock network.
- (6) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
- (7) The maximum ideal frequency is the SERDES factor (J) x the PLL maximum output frequency (fOUT) provided you can close the design timing and the signal integrity simulation is clean.
- (8) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.
- (9) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.
- (10) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.
- (11) The F<sub>MAX</sub> specification is based on the fast clock used for serial data. The interface F<sub>MAX</sub> is also dependent on the parallel clock domain which is design-dependent and requires timing analysis.
- (12) Stratix V RX LVDS will need DPA. For Stratix V TX LVDS, the receiver side component must have DPA.
- (13) Stratix V LVDS serialization and de-serialization factor needs to be x4 and above.
- (14) Requires package skew compensation with PCB trace length.
- (15) Do not mix single-ended I/O buffer within LVDS I/O bank.
- (16) Chip-to-chip communication only with a maximum load of 5 pF.
- (17) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

Table 38. LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for a Data Rate  $\geq$  1.25 Gbps

Jitter Fr	equency (Hz)	Sinusoidal Jitter (UI)
F1	10,000	25.000
F2	17,565	25.000
F3	1,493,000	0.350
F4	50,000,000	0.350

Figure 9 shows the **LVDS** soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate < 1.25 Gbps.

Figure 9. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate < 1.25 Gbps



## DLL Range, DQS Logic Block, and Memory Output Clock Jitter Specifications

Table 39 lists the DLL range specification for Stratix V devices. The DLL is always in 8-tap mode in Stratix V devices.

Table 39. DLL Range Specifications for Stratix V Devices (1)

C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
300-933	300-933	300-890	300-890	MHz

#### Note to Table 39:

(1) Stratix V devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Table 40 lists the DQS phase offset delay per stage for Stratix V devices.

Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices (1), (2) (Part 1 of 2)

Speed Grade	Min	Max	Unit
C1	8	14	ps
C2, C2L, I2, I2L	8	14	ps
C3,I3, I3L, I3YY	8	15	ps

Table 42. Memory Output Clock Jitter Specification for Stratix V Devices (1), (Part 2 of 2) (2), (3)

Clock Network	Parameter	Symbol	C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,I4		Unit
NEIWUIK			Min	Max	Min	Max	Min	Max	Min	Max	
	Clock period jitter	t <sub>JIT(per)</sub>	-25	25	-25	25	-30	30	-35	35	ps
PHY Clock	Cycle-to-cycle period jitter	t <sub>JIT(cc)</sub>	-50	50	-50	50	-60	60	-70	70	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-37.5	37.5	-37.5	37.5	-45	45	-56	56	ps

#### Notes to Table 42:

- (1) The clock jitter specification applies to the memory output clock pins generated using differential signal-splitter and DDIO circuits clocked by a PLL output routed on a PHY, regional, or global clock network as specified. Altera recommends using PHY clock networks whenever possible.
- (2) The clock jitter specification applies to the memory output clock pins clocked by an integer PLL.
- (3) The memory output clock jitter is applicable when an input jitter of 30 ps peak-to-peak is applied with bit error rate (BER) -12, equivalent to 14 sigma.

## **OCT Calibration Block Specifications**

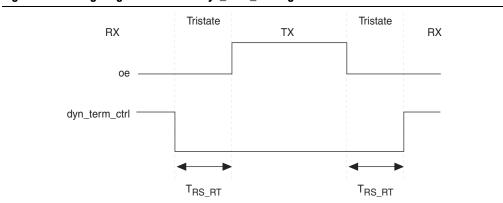
Table 43 lists the OCT calibration block specifications for Stratix V devices.

Table 43. OCT Calibration Block Specifications for Stratix V Devices

Symbol	Description	Min	Тур	Max	Unit
OCTUSRCLK	Clock required by the OCT calibration blocks	_	_	20	MHz
T <sub>OCTCAL</sub>	Number of OCTUSRCLK clock cycles required for OCT $\ensuremath{R}_{\ensuremath{S}}/\ensuremath{R}_{\ensuremath{T}}$ calibration		1000	_	Cycles
T <sub>OCTSHIFT</sub>	Number of OCTUSRCLK clock cycles required for the OCT code to shift out		32	_	Cycles
T <sub>RS_RT</sub>	Time required between the $\mathtt{dyn\_term\_ctrl}$ and oe signal transitions in a bidirectional I/O buffer to dynamically switch between OCT $R_S$ and $R_T$ (Figure 10)	_	2.5	_	ns

Figure 10 shows the timing diagram for the oe and dyn term ctrl signals.

Figure 10. Timing Diagram for oe and dyn\_term\_ctrl Signals



Page 58 Configuration Specification

Table 50 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is 1.

Table 50. FPP Timing Parameters for Stratix V Devices (1)

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CF2CD</sub>	nCONFIG low to CONF_DONE low	_	600	ns
t <sub>CF2ST0</sub>	nconfig low to nstatus low	_	600	ns
t <sub>CFG</sub>	nCONFIG low pulse width	2	_	μS
t <sub>STATUS</sub>	nstatus low pulse width	268	1,506 <sup>(2)</sup>	μ\$
t <sub>CF2ST1</sub>	nCONFIG high to nSTATUS high	_	1,506 <sup>(3)</sup>	μ\$
t <sub>CF2CK</sub> (6)	nCONFIG high to first rising edge on DCLK	1,506	_	μ\$
t <sub>ST2CK</sub> (6)	nSTATUS high to first rising edge of DCLK	2	_	μ\$
t <sub>DSU</sub>	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t <sub>DH</sub>	DATA[] hold time after rising edge on DCLK	0	_	ns
t <sub>CH</sub>	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CL</sub>	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t <sub>CLK</sub>	DCLK period	1/f <sub>MAX</sub>	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f <sub>MAX</sub>	DCLK frequency (FPP ×32)	_	100	MHz
t <sub>CD2UM</sub>	CONF_DONE high to user mode (4)	175	437	μS
+	GOVER DOVER high to GUVERN anabled	4 × maximum		
t <sub>CD2CU</sub>	CONF_DONE high to CLKUSR enabled	DCLK period	_	_
t <sub>CD2UMC</sub>	CONF_DONE high to user mode with CLKUSR option on	t <sub>CD2CU</sub> + (8576 × CLKUSR period) <sup>(5)</sup>	_	_

#### Notes to Table 50:

- (1) Use these timing parameters when the decompression and design security features are disabled.
- (2) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) This value is applicable if you do not delay configuration by externally holding the nstatus low.
- (4) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.
- (5) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (6) If nSTATUS is monitored, follow the t<sub>ST2CK</sub> specification. If nSTATUS is not monitored, follow the t<sub>CF2CK</sub> specification.

## FPP Configuration Timing when DCLK-to-DATA [] > 1

Figure 13 shows the timing waveform for FPP configuration when using a MAX II device, MAX V device, or microprocessor as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is more than 1.

Page 62 Configuration Specification

Table 53. AS Timing Parameters for AS  $\times$ 1 and AS  $\times$ 4 Configurations in Stratix V Devices (1), (2) (Part 2 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CD2UM</sub>	CONF_DONE high to user mode (3)	175	437	μS
t <sub>CD2CU</sub>	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t <sub>CD2UMC</sub>	CONF_DONE high to user mode with CLKUSR option on	$\begin{array}{c} t_{\text{CD2CU}} + (8576 \times \\ \text{CLKUSR period}) \end{array}$	_	_

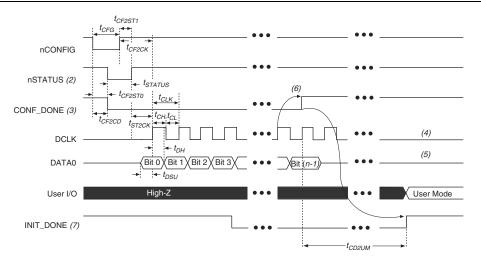
#### Notes to Table 53:

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- $(2) \quad t_{\text{CF2CD}}, t_{\text{CF2ST0}}, t_{\text{CFG}}, t_{\text{STATUS}}, \text{ and } t_{\text{CF2ST1}} \text{ timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63}.$
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

## **Passive Serial Configuration Timing**

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform (1)



#### Notes to Figure 15:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATAO is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

Page 64 I/O Timing

## **Remote System Upgrades**

Table 56 lists the timing parameter specifications for the remote system upgrade circuitry.

**Table 56. Remote System Upgrade Circuitry Timing Specifications** 

Parameter	Minimum	Maximum	Unit		
t <sub>RU_nCONFIG</sub> (1)	250	_	ns		
t <sub>RU_nRSTIMER</sub> (2)	250	_	ns		

#### Notes to Table 56:

- (1) This is equivalent to strobing the reconfiguration input of the ALTREMOTE\_UPDATE megafunction high for the minimum timing specification. For more information, refer to the Remote System Upgrade State Machine section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (2) This is equivalent to strobing the reset\_timer input of the ALTREMOTE\_UPDATE megafunction high for the minimum timing specification. For more information, refer to the User Watchdog Timer section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

## **User Watchdog Internal Circuitry Timing Specification**

Table 57 lists the operating range of the 12.5-MHz internal oscillator.

**Table 57. 12.5-MHz Internal Oscillator Specifications** 

Minimum	Typical	Maximum	Units		
5.3	7.9	12.5	MHz		

## I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O Timing and the Quartus II Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

You can download the Excel-based I/O Timing spreadsheet from the Stratix V Devices Documentation web page.

## **Programmable IOE Delay**

Table 58 lists the Stratix V IOE programmable delay settings.

Table 58. IOE Programmable Delay for Stratix V Devices (Part 1 of 2)

Borometer Aveilable Mir		Min	Fast	Slow Model								
Parameter (1)	Available Settings	Offset (2)	Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D1	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D2	32	0	0.230	0.244	0.415	0.415	0.459	0.503	0.417	0.456	0.500	ns

Page 66 Glossary

Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions		
G				
Н	_	<del>-</del>		
1				
J	JTAG Timing Specifications	High-speed I/O block—Deserialization factor (width of parallel data bus).  JTAG Timing Specifications:  TMS  TDI  TCK  TJPSU  TJ		
K L M N	_			
P	PLL Specifications	Diagram of PLL Specifications (1)  CLKOUT Pins  Four Core Clock  Reconfigurable in User Mode  External Feedback  Note:  (1) Core Clock can only be fed by dedicated clock input pins or PLL outputs.		
Q	_	<del>-</del>		
R	R <sub>L</sub>	Receiver differential input discrete resistor (external to the Stratix V device).		
	_ <u>-</u>	1		

Glossary Page 67

Table 60. Glossary (Part 3 of 4)

Letter	Subject	Definitions							
	SW (sampling window)	Timing Diagram—the period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window, as shown:  Bit Time  0.5 x TCCS RSKM Sampling Window (SW)  0.5 x TCCS							
S	Single-ended voltage referenced I/O standard	The JEDEC standard for <b>SSTL</b> and <b>HSTL</b> I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state.  The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing:  Single-Ended Voltage Referenced I/O Standard  VIHACO  VIHACO  VILLOCO  V							
	t <sub>C</sub>	High-speed receiver and transmitter input and output clock period.							
	TCCS (channel- to-channel-skew)	The timing difference between the fastest and slowest output edges, including $t_{\rm CO}$ variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the <i>Timing Diagram</i> figure under <b>SW</b> in this table).							
		High-speed I/O block—Duty cycle on the high-speed transmitter output clock.							
Т	t <sub>DUTY</sub>	Timing Unit Interval (TUI)  The timing budget allowed for skew, propagation delays, and the data sampling window.  (TUI = $1/(\text{receiver input clock frequency multiplication factor}) = t_{\text{C}}/w$ )							
	t <sub>FALL</sub>	Signal high-to-low transition time (80-20%)							
	t <sub>INCCJ</sub>	Cycle-to-cycle jitter tolerance on the PLL clock input.							
	t <sub>OUTPJ_IO</sub>	Period jitter on the general purpose I/O driven by a PLL.							
	t <sub>OUTPJ_DC</sub>	Period jitter on the dedicated clock output driven by a PLL.							
	t <sub>RISE</sub>	Signal low-to-high transition time (20-80%)							
U	_								